Electronic Patent Application Fee Transmittal								
Application Number:	105	10591476						
Filing Date:	01-Sep-2006							
Title of Invention:	Copper film deposition method							
First Named Inventor/Applicant Name:	Yasuhiko Kojima							
Filer:	Michael A. Makuch/Cynthia Johnson							
Attorney Docket Number:	33082M343							
Filed as Large Entity								
U.S. National Stage under 35 USC 371 Filing Fees								
Description		Fee Code	Quantity	Amount	Sub-Total in USD(\$)			
Basic Filing:								
Pages:								
Claims:								
Miscellaneous-Filing:								
Petition:								
Patent-Appeals-and-Interference:								
Notice of appeal		1401	1	540	540			
Post-Allowance-and-Post-Issuance:								
Extension-of-Time:								

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension - 3 months with \$0 paid	1253	1	1110	1110
Miscellaneous:				
	Total in USD (\$)			1650